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Renesas Technology Corp. Customer Support Dept. April 1, 2003



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3-to-8-line Decoder/Demultiplexer



ADE-205-470 (Z) 1st. Edition Sep. 2000

Description

The HD74HC238 has 3 binary select inputs (A, B and C). If the device is enabled these inputs determine which one of the eight normally high outputs will go low. Two active low and one active high enables (G_1 , $\overline{G_{2A}}$ and $\overline{G_{2B}}$) are provided to ease the cascading of decoders.

Features

• High Speed Operation: t_{pd} (Data to Y) = 15 ns typ ($C_L = 50 \text{ pF}$)

• High Output Current: Fanout of 10 LSTTL Loads

• Wide Operating Voltage: $V_{CC} = 2 \text{ to } 6 \text{ V}$

• Low Input Current: 1 μA max

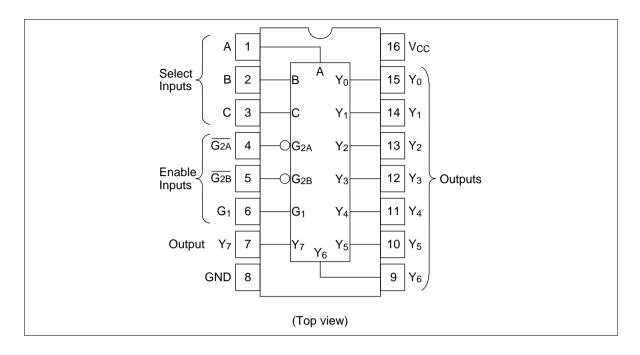
• Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

Function Table

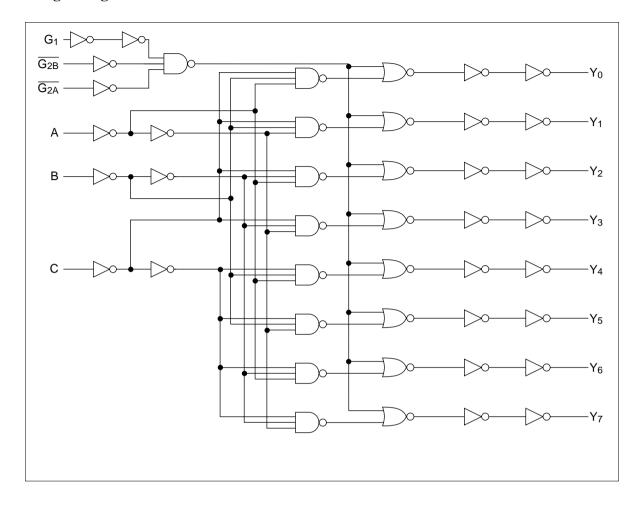
Inputs

Enable			Select			Outputs							
G ₁	G _{2A}	$\overline{G_{\scriptscriptstyle 2B}}$	С	В	Α	Y ₀	Y ₁	Y ₂	Y ₃	Y ₄	Y ₅	Y ₆	Y ₇
Χ	Χ	Н	Х	Χ	Χ	L	L	L	L	L	L	L	L
X	Н	Χ	Х	Х	Χ	L	L	L	L	L	L	L	L
L	Χ	Χ	Х	Х	Χ	L	L	L	L	L	L	L	L
Н	L	L	L	L	L	Н	L	L	L	L	L	L	L
Н	L	L	L	L	Н	L	Н	L	L	L	L	L	L
Н	L	L	L	Н	L	L	L	Н	L	L	L	L	L
Н	L	L	L	Н	Н	L	L	L	Н	L	L	L	L
Н	L	L	Н	L	L	L	L	L	L	Н	L	L	L
Н	L	L	Н	L	Н	L	L	L	L	L	Н	L	L
Н	L	L	Н	Н	L	L	L	L	L	L	L	Н	L
Н	L	L	Н	Н	Н	L	L	L	L	L	L	L	Н

Pin Arrangement



Logic Diagram



DC Characteristics

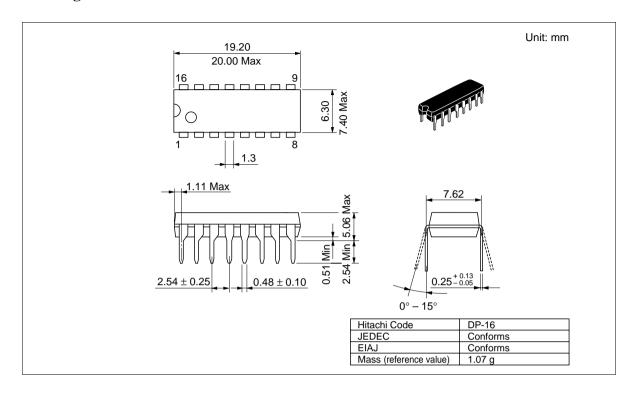
			Ta = 25°C		Ta = −40 to +85°C		_			
Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Condition	าร
Input voltage	V _{IH}	2.0	1.5	_	_	1.5	_	V		
		4.5	3.15	i —		3.15	_	_		
		6.0	4.2	_	_	4.2	_	_		
	V _{IL}	2.0	_	_	0.5	_	0.5	V		
		4.5	_	_	1.35	_	1.35	_		
		6.0	_	_	1.8	_	1.8	=		
Output voltage	V _{OH}	2.0	1.9	2.0	_	1.9	_	V	Vin = V _{IH} or V _{IL}	$I_{OH} = -20 \mu A$
		4.5	4.4	4.5	_	4.4	_	=		
		6.0	5.9	6.0	_	5.9	_	=		
		4.5	4.18	3 —	_	4.13	_	=		I _{OH} = -4 mA
		6.0	5.68	3 —	_	5.63	_	=		$I_{OH} = -5.2 \text{ mA}$
	V _{OL}	2.0	_	0.0	0.1	_	0.1	V	Vin = V _{IH} or V _{IL}	I _{OL} = 20 μA
		4.5	_	0.0	0.1	_	0.1	=		
		6.0	_	0.0	0.1	_	0.1	=		
		4.5	_	_	0.26	_	0.33	=		I _{OL} = 4 mA
		6.0	_	_	0.26	_	0.33	_		I _{OL} = 5.2 mA
Input current	lin	6.0	_	_	±0.1	_	±1.0	μΑ	Vin = V _{CC} or GN	ND
Quiescent supply current	I _{cc}	6.0	_		4.0	_	40	μΑ	$Vin = V_{CC} \text{ or } GN$	ND, lout = $0 \mu A$

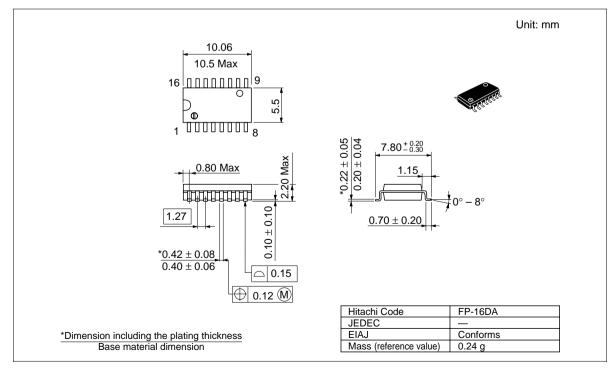
AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

Ta = -40 to Ta = 25°C +85°C

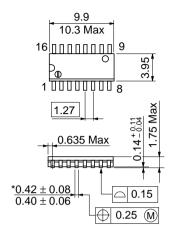
Item	Symbol	V_{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Propagation delay	t _{PLH}	2.0	_	_	150	_	190	ns	Select to Y
time	$t_{\tiny PHL}$	4.5	_	15	30	_	38		
		6.0	_	_	26	_	33		
		2.0	_	_	150	_	190	ns	Enable to Y
		4.5	_	13	30	_	38	_	
		6.0	_	_	26	_	33	_	
Output rise/fall	t _{TLH}	2.0	_	_	75	_	95	ns	
time	t_{THL}	4.5	_	5	15	_	19	=	
		6.0	_	_	13	_	16	_	
Input capacitance	Cin	_	_	5	10	_	10	pF	

Package Dimensions

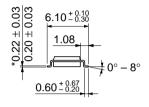




Unit: mm







*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN						
JEDEC	Conforms						
EIAJ	Conforms						
Mass (reference value)	0.15 g						

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